1 Package summary

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>package length</td>
<td>4.9</td>
<td>5</td>
<td>5.1</td>
<td>mm</td>
</tr>
<tr>
<td>package width</td>
<td>4.9</td>
<td>5</td>
<td>5.1</td>
<td>mm</td>
</tr>
<tr>
<td>seated height</td>
<td>-</td>
<td>0.85</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>nominal pitch</td>
<td>-</td>
<td>0.5</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>actual quantity of termination</td>
<td>-</td>
<td>32</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>
2 Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

Figure 1. Package outline HVQFN32 (SOT617-3)
3 Soldering

Footprint information for reflow soldering of HVQFN32 package

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Figure 2. Reflow soldering footprint for HVQFN32 (SOT617-3)
4 Legal information

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